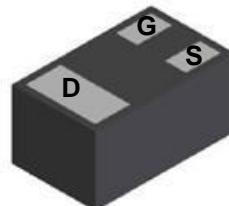


## **WPM2092A**

**Single P-Channel, -20V, -1.2A, Power MOSFET**

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

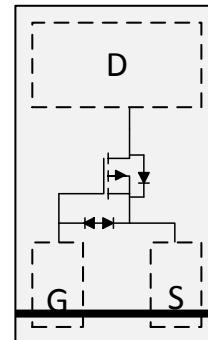
<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>DS(on)</sub> (mΩ)</b>
<b>-20</b>	230@ V <sub>GS</sub> =-4.5V
	320@ V <sub>GS</sub> =-2.8V
	355@ V <sub>GS</sub> =-2.5V
	650@ V <sub>GS</sub> =-1.8V
ESD Rating: 2000V HBM	



**DFN1006-3L**

### **Descriptions**

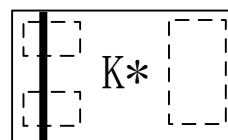
The WPM2092A is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS (ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM2092A is Pb-free.



### **Features**

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package DFN1006-3L

**Pin configuration (Top view)**



K = Device Code

\* = Month(A-Z)

### **Marking**

### **Applications**

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

### **Order information**

<b>Device</b>	<b>Package</b>	<b>Shipping</b>
WPM2092A-3/TR	DFN1006-3L	10K/Reel&Tape

## Absolute Maximum ratings

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	±10	V
Gate-Source Voltage	V <sub>GS</sub>	±10		
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-1.20	A
	T <sub>A</sub> =70°C		-0.97	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.86	W
	T <sub>A</sub> =70°C		0.55	
Continuous Drain Current <sup>b</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-0.70	A
	T <sub>A</sub> =70°C		-0.56	
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.28	W
	T <sub>A</sub> =70°C		0.18	
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>		-1.5	A
Operating Junction Temperature	T <sub>J</sub>		-55 to 150	°C
Lead Temperature	T <sub>L</sub>		260	°C
Storage Temperature Range	T <sub>stg</sub>		-55 to 150	°C

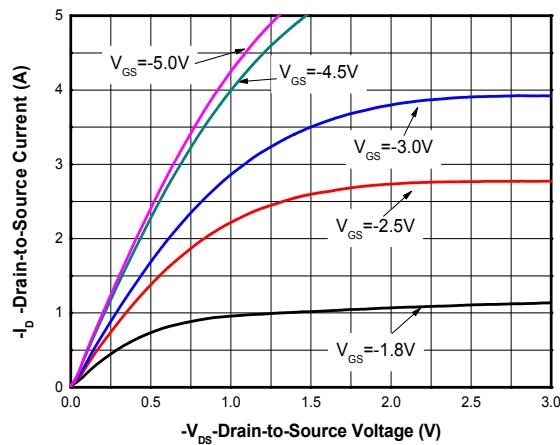
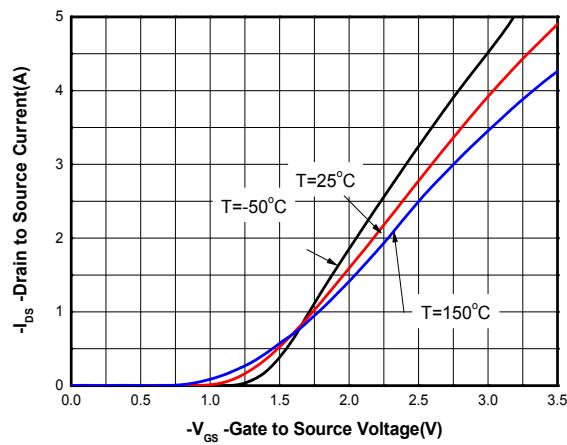
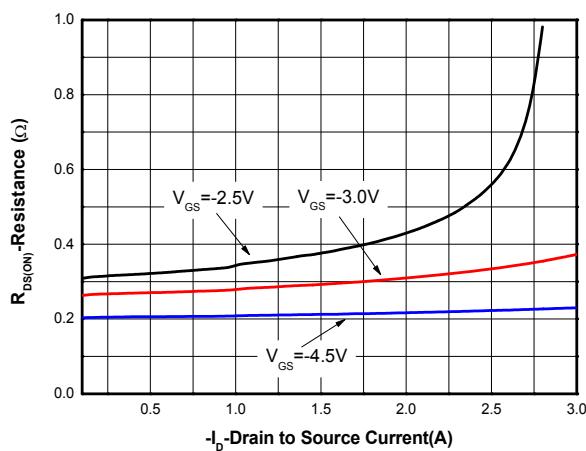
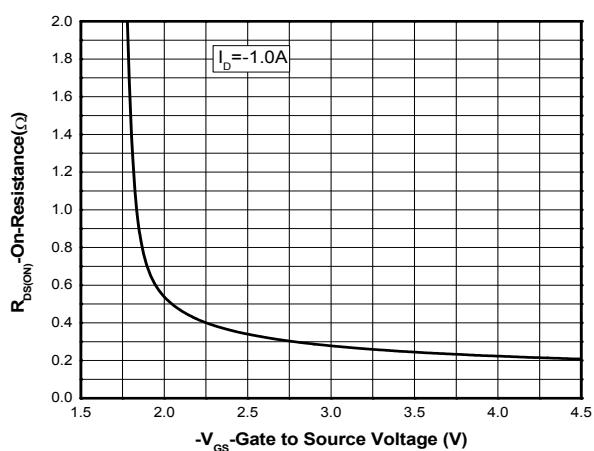
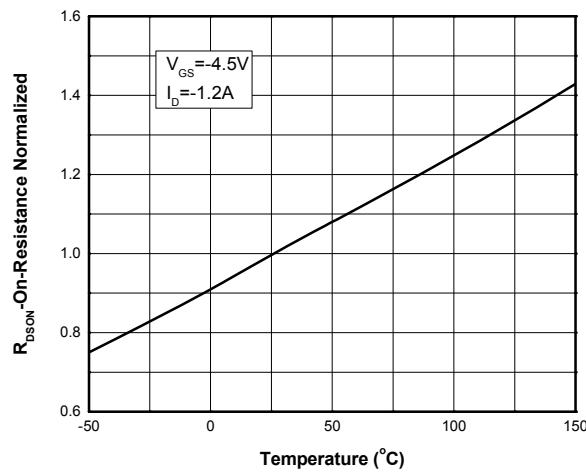
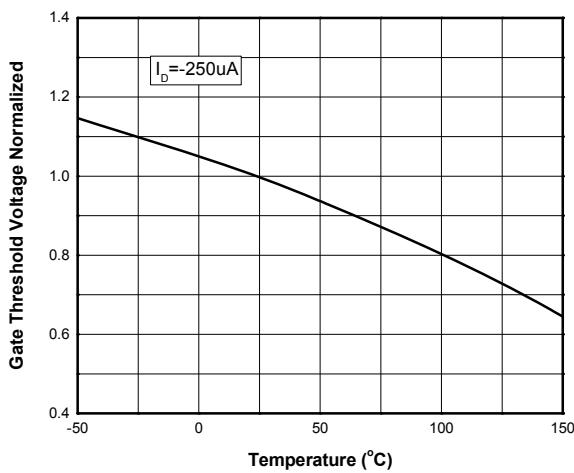
## Thermal resistance ratings

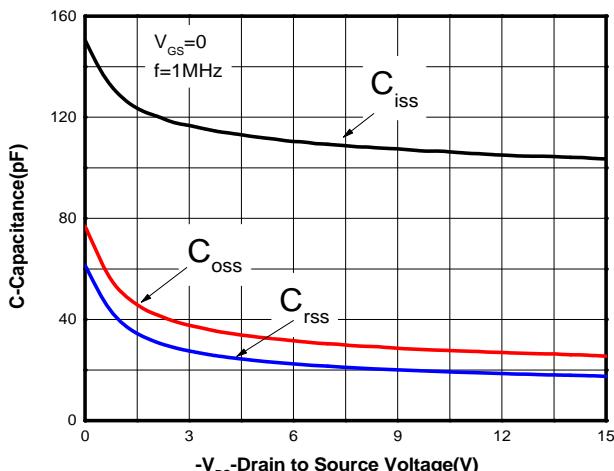
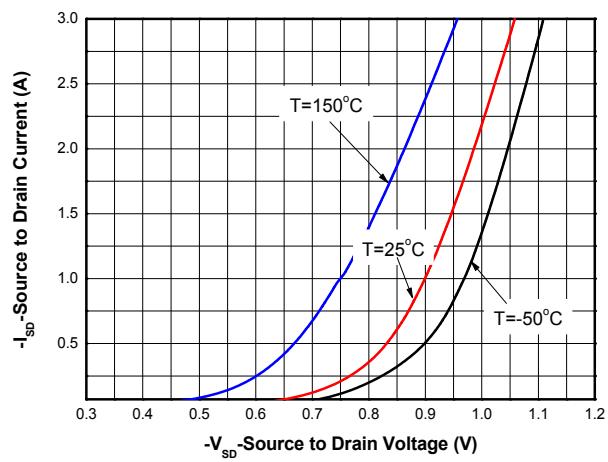
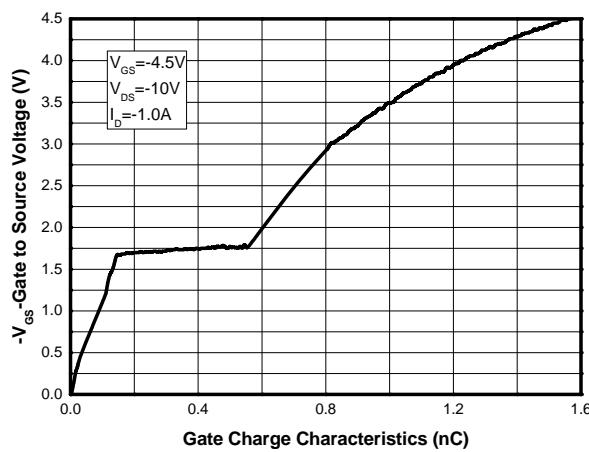
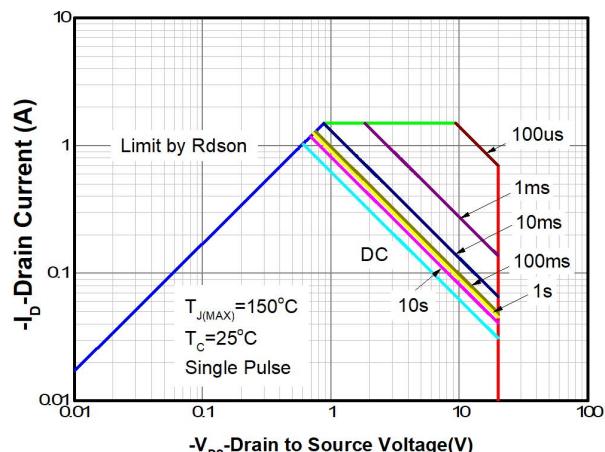
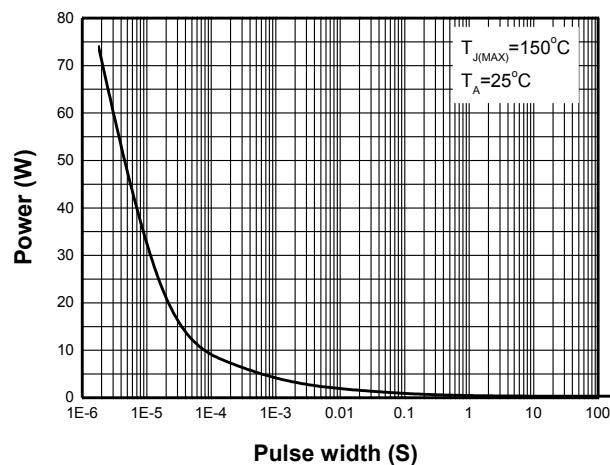
Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	73	146
	Steady State		101	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t ≤ 10 s	R <sub>θJA</sub>	201	402
	Steady State		253	

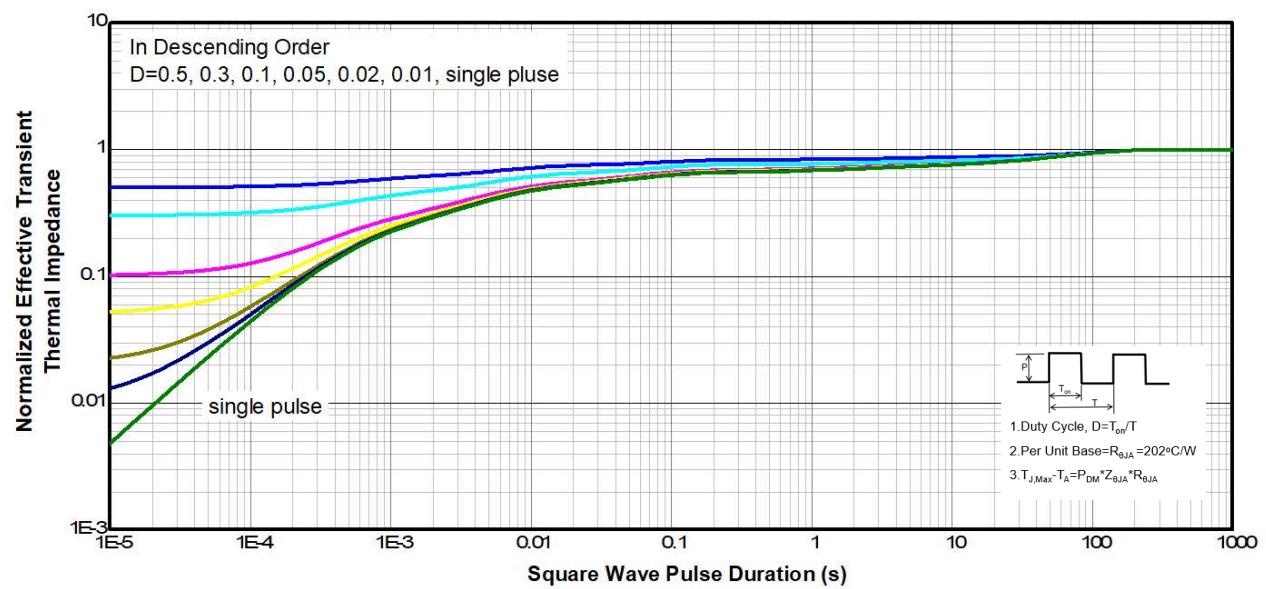
- a The value of R<sub>θJA</sub> is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with TA =25°C. The value in any given application is determined by the user's specific board design.
- b The power dissipation P<sub>D</sub> is based on Junction-to-Ambient thermal resistance R<sub>θJA</sub> t≤10s value and the T<sub>J(MAX)</sub>=150°C.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial T<sub>J</sub> =25°C, the maximum allowed junction temperature of 150°C.
- d The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

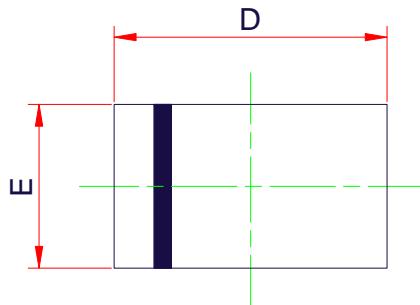
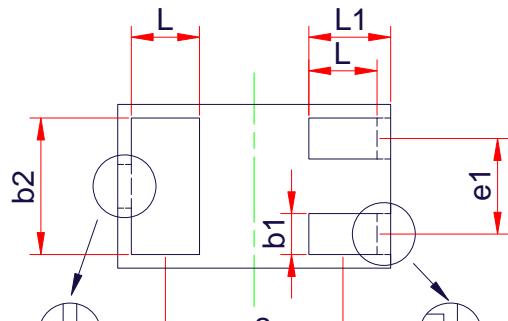
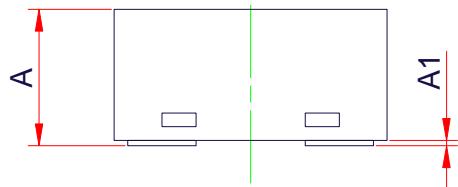
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$V_{DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -16 \text{ V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8\text{V}$			$\pm 1$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.45	-0.7	-1.0	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -1.2\text{A}$		230	390	$\text{m}\Omega$
		$V_{GS} = -2.8\text{V}, I_D = -0.8\text{A}$		320	480	
		$V_{GS} = -2.5\text{V}, I_D = -0.6\text{A}$		355	620	
		$V_{GS} = -1.8\text{V}, I_D = -0.5\text{A}$		650	790	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}, V_{DS} = -15 \text{ V}$		104		$\text{pF}$
Output Capacitance	$C_{OSS}$			25		
Reverse Transfer Capacitance	$C_{RSS}$			19		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5 \text{ V}, V_{DS} = -10 \text{ V}, I_D = -1\text{A}$		1.1		$\text{nC}$
Threshold Gate Charge	$Q_{G(TH)}$			0.25		
Gate-to-Source Charge	$Q_{GS}$			0.38		
Gate-to-Drain Charge	$Q_{GD}$			0.47		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -4.5 \text{ V}, V_{DS} = -10 \text{ V}, R_G = 6 \Omega, I_D = -1\text{A}$		7.2		$\text{ns}$
Rise Time	$t_r$			7.5		
Turn-Off Delay Time	$t_{d(OFF)}$			18.5		
Fall Time	$t_f$			10.7		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0 \text{ V}, I_S = -0.5\text{A}$	-0.5	-0.8	-1.2	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-Source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**

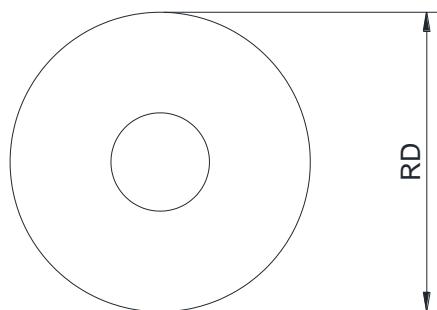
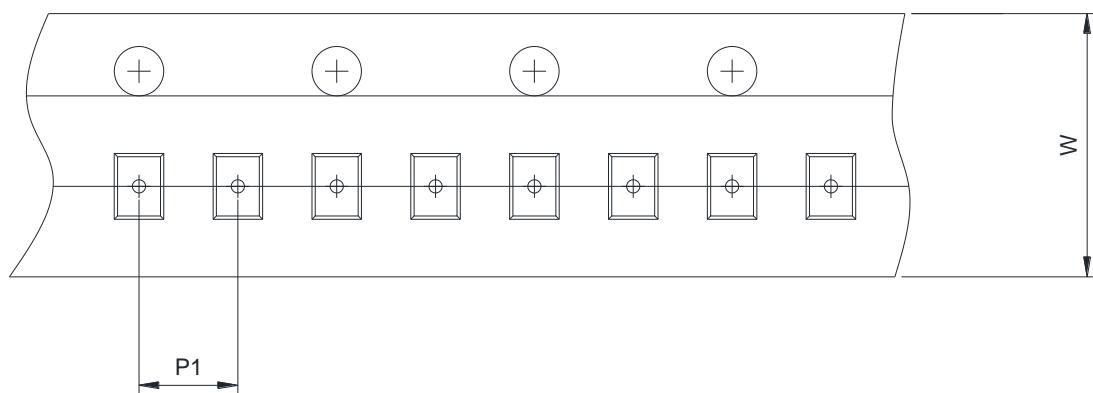
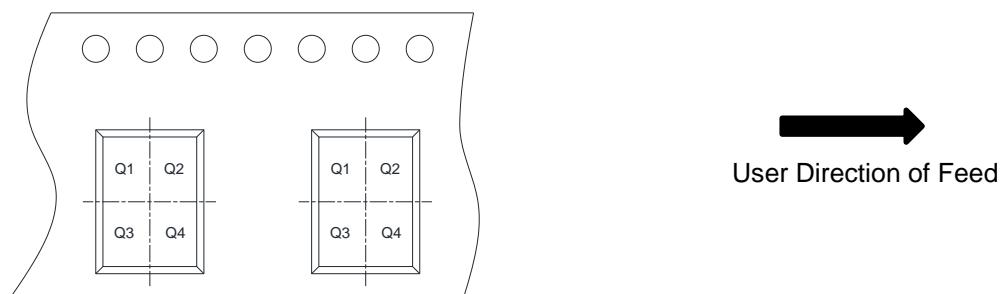

**Capacitance**

**Body diode forward voltage**

**Gate Charge Characteristics**

**Safe operating power**

**Single pulse power**



**Transient thermal response (Junction-to-Ambient)**

**PACKAGE OUTLINE DIMENSIONS**
**DFN1006-3L**

**TOP VIEW**

**BOTTOM VIEW**

**SIDE VIEW**

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.36	-	0.50
A1	0.00	-	0.05
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.40	0.50	0.60
L	0.20	0.25	0.30
L1	0.20	0.30	0.40
e1	0.35 BSC		
e2	0.65 BSC		

**Package outline dimensions**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


<b>RD</b>	<b>Reel Dimension</b>	<input checked="" type="checkbox"/> 7inch <input type="checkbox"/> 13inch
<b>W</b>	<b>Overall width of the carrier tape</b>	<input checked="" type="checkbox"/> 8mm <input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
<b>P1</b>	<b>Pitch between successive cavity centers</b>	<input checked="" type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input type="checkbox"/> 8mm
<b>Pin1</b>	<b>Pin1 Quadrant</b>	<input type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input checked="" type="checkbox"/> Q4